



Material Content Data Sheet



Halogen-Free

Sales Product Name	ISC012N04LM6	Issued	11. August 2021
MA#	MA005559703		
Package	PG-TDSON-8-36	Weight*	115.13 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.182	1.03	1.03	10264	10264
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		135	
	non noble metal	iron	7439-89-6	0.052	0.04		450	
	non noble metal	copper	7440-50-8	51.740	44.94	44.99	449413	449998
wire	noble metal	gold	7440-57-5	0.043	0.04	0.04	377	377
encapsulation	organic material	carbon black	1333-86-4	0.082	0.07		708	
	plastics	epoxy resin	-	6.442	5.60		55955	
	inorganic material	silicondioxide	60676-86-0	34.249	29.75	35.42	297483	354146
leadfinish	non noble metal	tin	7440-31-5	1.392	1.21	1.21	12087	12087
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1683	1683
solder	non noble metal	tin	7440-31-5	0.031	0.03		265	
	noble metal	silver	7440-22-4	0.038	0.03		331	
	non noble metal	lead	7439-92-1	1.457	1.27	1.33	12653	13249
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	non noble metal	copper	7440-50-8	17.131	14.88	14.89	148802	148996
clip plating	noble metal	silver	7440-22-4	1.059	0.92	0.92	9200	9200
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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